





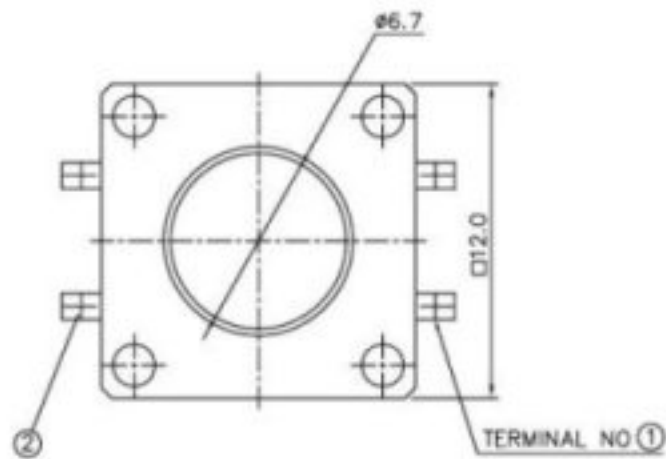
MATERIAL	SPECIFICATION LIST
	TACT SWITCH

5. AUTOMATIC SOLDERING CONDITIONS

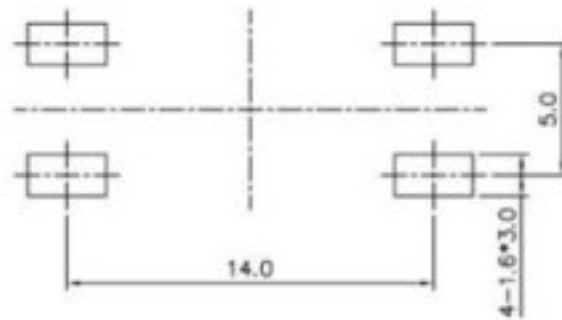
(in case the automatic flow soldering is to be used)

- 5.1 Soldering Temperature 240°C max
- 5.2 Soldering Time Continuous dipping duration shall not exceed 5 second
- 5.3 Permissible Soldering Times
  - 2 time max
  - (Twice soldering would be dipped after the temperature goes down to a normal temperature.)
- 5.4 Preheat temperature 100°C max,  
(Circumferential temperature of the printed wiring board)
- 5.5 Preheat Time 45seconds max,
- 5.6 Flux streaming Flux streaming shall be controlled so that it shall not swell beyond the printed wiring board where components are installed
- 5.7 Other Precautions
  - (1) Flux shall not be applied to switch terminals and the part mounting surface of the P.W. board before soldering
  - (2) Do not wash to switch after soldering

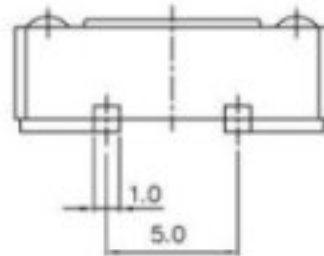
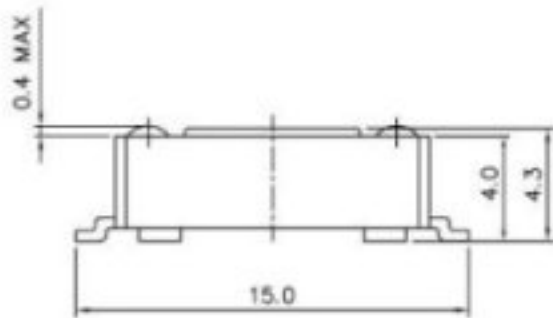
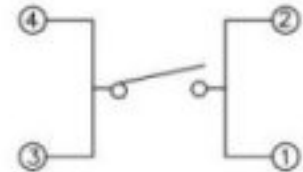
					APPD	CHKD	DSGD	TITLE
								<b>SMD TYPE</b>
								DOCUMENT NO.
ZONE	SYMB	DATE	APPD	CHKD	DSGD			HT0102



PCB DIMENSION



CIRCUIT DIAGRAM



NOTE

1. RATING : DC 12V 50mA
2. OPERATING FORCE : 160±50gf, 260±50gf
3. TRAVEL : 0.25  $\begin{smallmatrix} +0.2 \\ -0.1 \end{smallmatrix}$  m/m
4. CONTACT RESISTANCE : 100mΩ MAX
5. MANUFACTURING SPECIFICATION WOULD BE ACCORDANCE WITH HT0102

PART NO	PART NAME	Q'TY	MATERIAL	STANDARD	DISPOSITION	REMARKS
△			TRIGON- OMETRY	UNIT	SCALE	<b>TACT SWITCHES</b>
△				3	1	
△			APPD	CHKD	DSGD	
△						
△						
NO	CORRECTION				MODEL	<b>CTP1212S</b>